Serial No.: 09/930,747

#### <u>REMARKS</u>

The present amendment is in response to the Office Action dated September 26, 2002, where the Examiner has rejected claims 1-20. By the present amendment, claims 1, 13 and 20 have been amended. Accordingly, claims 1-20 are pending in the application. The Examiner is respectfully requested to reconsider and allow claims 1-20 pending in the present application.

### A. Rejection of Claims 1, 2, 5-14 and 17-20 Under 35 USC § 102(b)

The Examiner has rejected claims 1, 2, 5-14 and 17-20 under 35 USC § 102(b) as being anticipated by Selna (USPN 5,640,048) ("Selna '048"). Applicant respectfully disagrees; however, in order to expedite the prosecution of this application, applicant has amended independent claims 1 and 13 to further recite "said conductor having a first terminal and a second terminal, each of said first and second terminals situated on said top surface of said substrate." For the reasons that follow, applicant respectfully submits that claims 1 and 13 are patentably distinguishable over Selna '048.

The Examiner has cited Selna '048 and, in particular, Figure 2 of Selna '048, indicating that Selna '048 discloses, among other things, "a structure comprising a substrate (52, 54) having a top surface for receiving a die 12; a conductor (8B, left) being adapted for connection to a first substrate signal bond pad (10B, bottom left) and a second terminal (8A, left) of said conductor being adapted for connection to a first die signal bond pad (not labeled but inherently present)."

(Page 2 of the Detailed Action, Office Action dated September 26, 2002).

Applicant respectfully submits that the structure recited in independent claims 1 and 13 of the present application is a significant departure from the package disclosed in Selna '048.

Element 8A of Figure 2 in Selna '048 is essentially a conducive trace for connection to a power

Serial No.: 09/930,747

source (Vdd) whereas element 8B of Figure 2 is Selna '048 is a conductive trace for connection to electrical signals. The description associated with Figure 1 of Selna '048 sets forth the above description in greater detail (see, e.g., col. 2:3-24). Thus, traces 8A and 8B of Selna are essentially two separate electrical paths, i.e., 8A for Vdd, and 8B for electrical signals, and therefore are not electrically tied to each other to form a single conductor. In contrast, the conductor recited in claims 1 and 13 is a single conductor including first and second terminals, where each of the first and second terminals is situated on the top surface of the substrate.

Furthermore, as recited in amended claim 1, the conductor is "patterned on said top surface of said substrate," and the first terminal is "adapted for connection to a first substrate signal bond pad" while the second terminal is "adapted for connection to a first die signal bond pad," where each of the first substrate signal pad and the first die signal bond pad is situated on the top surface of the substrate. Selna '048 neither discloses nor remotely suggests the establishing of the structure and the connections between the first and second conductor terminals and the first substrate signal pad and the first die signal bond pad, respectively, as specified in claim 1.

With regard to amended claim 13, claim 13 has further been amended to specify that the "conductor further comprises an inductor." Thus, the conductor specified in claim 13 provides an inductance between the first terminal and the second terminal. Selna '048 neither discloses nor remotely suggests providing inductance between traces 8A and 8B. As pointed out above, trace 8A is utilized for connection to Vdd, while trace 8B is utilized for connection to electrical signals. Therefore, traces 8A and 8B provide two separate electrical paths, and are neither disclosed nor suggested by Selna '048 as providing inductance therebetween, as set forth in claim 13.

Serial No.: 09/930,747

Accordingly, it is respectfully submitted that rejection of independent claim 1 and its dependent claims 2-12 has been traversed and that claims 1-12 should now be allowed. For similar reasons, it is respectfully submitted that rejection of independent claim 13 and its dependent claims 14-20 has been traversed and that claims 13-20 should now be allowed

## B. Rejection of Claims 3-4 and 15-16 Under 35 USC § 103(a)

The Examiner has further rejected dependent claims 3-4 and 15-16 under 35 USC § 103(a) as being unpatentable over Selna '048. As discussed above, independent claims 1 and 13 are patentably distinguishable over Selna '048 and, as such, claims 3-4 depending from independent claim 1 and claims 15-16 depending from independent claim 13 are, *a fortiori*, also patentably distinguishable over Selna '048.

# C. Rejection of Claims 1-20 under the Judicially Created Doctrine of Double Patenting

The Examiner has rejected claims 1-20 under the judicially created doctrine of double patenting as being unpatentable over claims 18-33 and 58-66 of U.S. Application No. 09/713,834, or alternatively over claims 1-17 of U.S. Patent No. 6,191,477, in view of Selna '048. As discussed above, claims 1-20 are patentably distinguishable over Selna '048. Accordingly, applicant respectfully submits that rejection of claims 1-20 under the judicially created doctrine of double patenting as being unpatentable over claims 18-33 and 58-66 of U.S. Application No. 09/713,834, or alternatively over claims 1-17 of U.S. Patent No. 6,191,477, in view of Selna '048, has been traversed, and that claims 1-20 should be allowed.

Serial No.: 09/930,747

#### D. Conclusion

For all the foregoing reasons, claims 1-20 pending in the present application are now in condition for allowance and an early Notice of Allowance directed to pending claims 1-20 is respectfully requested.

Respectfully Submitted; FARJAMI & FARJAMI LLP

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Lori Llave

Name

Signature

Serial No.: 09/930,747

## VERSION WITH MARKINGS TO SHOW CHANGES MADE

#### In the Claims:

#### Claims 1, 13 and 20 have been amended as follows:

1. (Once Amended) A structure comprising:

a substrate having a top surface for receiving a die;

a conductor patterned on said top surface of said substrate, <u>said conductor having a first</u> terminal and a second terminal, each of said first and second terminals situated on said top <u>surface of said substrate</u>, <u>said</u> a first terminal of said conductor being adapted for connection to a first substrate signal bond pad, <u>said first substrate signal bond pad situated on said top surface of said substrate</u> and <u>said</u> a second terminal of said conductor being adapted for connection to a first die signal bond pad, <u>said first die signal bond pad situated on said top surface of said substrate</u>;

a printed circuit board attached to a bottom surface of said substrate;

at least one via in said substrate;

said at least one via providing an electrical connection between a second die signal bond pad and said printed circuit board.

13. (Once Amended) A structure comprising:

a substrate having a top surface for receiving a die;

a conductor patterned within said substrate, said conductor comprising an inductor, said conductor having a first terminal and a second terminal, each of said first and second terminals situated on said top surface of said substrate, a first substrate signal bond pad being said a first

Serial No.: 09/930,747

terminal of said conductor and a second substrate signal bond pad being <u>said</u> a second terminal of said conductor;

a printed circuit board attached to a bottom surface of said substrate;

at least one via in said substrate;

said at least one via providing an electrical connection between a die signal bond pad and said printed circuit board.

20. (Once Amended) The structure of claim 19 wherein said conductor is an solenoid inductor.